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Invensas to Exhibit Low Temperature Wafer Bonding and 3D Interconnect Solutions at IWLPC 2016

SAN JOSE, Calif.--(BUSINESS WIRE)-- Tessera Technologies, Inc. (Nasdaq:TSRA), announced today that its wholly owned subsidiary Invensas Corporation will exhibit its low temperature wafer bonding and 3D interconnect solutions at the upcoming International Wafer-Level Packaging Conference 2016, taking place October 18-20 in San Jose, Calif.

At the show, Guilian Gao, Ph.D., Principal Engineer at Invensas will deliver a presentation titled, "Direct Bond Interconnect (DBI®) Technology as an Alternative to Thermal Compression Bonding." Additionally, Min Tao, Senior Manager of Advanced Packaging at Invensas will deliver a presentation titled, "Package-on-Package Interconnect for Fan-Out Wafer-Level Packages."

What: IWLPC 2016
Date: October 18-20, 2016
Location: Doubletree by Hilton Hotel, San Jose, California
Booth Number: 41
Registration Information: Conference attendees can register for the show at http://www.iwlpc.com/register_now.cfm.
Details: At the show, Invensas will highlight its advanced wafer bonding technology, ZiBond®, a low temperature homogeneous, direct bonding technology that forms a strong bond between wafers or die with same or different coefficients of thermal expansion. Invensas will also exhibit Direct Bond Interconnect (DBI), its hybrid direct bonding technology for wafer and die level 3D interconnect applications.

For more information about Invensas' advanced semiconductor packaging technologies, visit www.invensas.com.

About Tessera Technologies, Inc.

Tessera Technologies, Inc., including its Invensas and FotoNation subsidiaries, licenses technologies and intellectual property to customers for use in areas such as mobile computing and communications, memory and data storage, and 3D IC technologies, among others. Our technologies include semiconductor packaging and interconnect solutions, and computational imaging and computer vision products and solutions for mobile and other vision systems. For more information call +1.408.321.6000 or visit www.tessera.com or www.invensas.com.

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